	CONNECTING CONNECTING CONNECTING CONNECTING CONNECTING CONNECTING CONNECTING CONNECTING CONNECTING	PC, Bannockl	burn, Illinois. A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declaration	tion of th encompa	ne substances asses all lowe	within the er level mat	manufactur erials for wl	er listed ite hich the ma	em. Note: anufactur	: if the item is an a rer has engineering	ssembly with low responsibility.
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type   http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information				
upplier	Information														
Company name* Company unique ID					1	Unique ID Authority					Response Date*				
nsemi												2024-05-	)5		
ontact Na	ame		Title - Contact			]	Phone - Contact*					Email - Contact*			
Product-E	Inv-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized	l Representative*	Title - Repres	Title - Representative			Phone - Representative*				Email - Representative*					
roduct-E	nv-Stewards	Product Envi	oduct Enviro Compliance NA				A				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Iten		Number Mfr Item Name			Effective Date	ffective Date Version Manufacturing Sit		ing Site	V	/eight*	UOM	Unit Type		
		AR0822 A0-DP	NPSM10SMT	8MP 1/2 CIS SO	mono		2024-05-05		,	TWU		4	30.4	mg	Each
Ianufac	cturing Proccess Informa	tion													
,	Terminal Plating / Grid Array Material		Ferminal Base A	nal Base Alloy J-STD-020 MSI		L Rating	Peak Proc	Peak Process Body Temperatu		ure Max Time at Peak Tempera		Temperatu	re Nun	nber of Reflow Cy	cles
SnAgCu CU Al		CU Alloy		4		260		C 30		seconds 3					
omments															
or more i	nformation regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
hirective 2015/863/EU amending RoHS RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lea (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted					
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	33.19	mg	Supplier	Silicon (Si)	7440-21-3	<b>_</b>	33.19	mg
Die Attach	2.29	mg	Supplier	3,4-EPOXYCYCLOHEXYLMETHYL	2386-87-0		0.1374	mg
			Supplier	1,6-Bis(2,3-epoxypropoxy)naphthalene	27610-48-6		1.7633	mg
			Supplier	Inorganic filler	7727-43-7, 14807- 96-6		0.3893	mg
Die Attach Epoxy	2.15	mg	Supplier	Tridymite	15468-32-3		0.1075	mg
			Supplier	2,2-bis(acryloyloxymethyl)butyl acrylate	15625-89-5		1.6125	mg
			Supplier	Imidazole Addition	68490-66-4		0.0538	mg
			Supplier	Epoxy Phenol Novolak Resin	28064-14-4		0.3762	mg
maging Lens	88.79	mg	Supplier	Sulfur (S)	7704-34-9		0.4439	mg
			Supplier	Titanium Dioxide (TiO2)	13463-67-7		4.4395	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		4.4395	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		4.4395	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		4.4395	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		4.4395	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		4.4395	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		61.709	mg
Mold Compound	142.43	mg		Epoxy resin	proprietary data		2.1364	mg
			Supplier	Hardener	Proprietary Data		7.1215	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		10.6823	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2849	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		122.2049	mg
older Ball	42.7	mg	Supplier	Silver (Ag)	7440-22-4		1.281	mg
			Supplier	Tin (Sn)	7440-31-5		41.2055	mg
			Supplier	Copper (Cu)	7440-50-8		0.2135	mg
ubstrate	118.4	mg	Supplier	Bismaleimide Resin	105391-33-1		15.4867	mg
			Supplier	Talc	14807-96-6		1.5487	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		25.1008	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.386	mg
			Supplier	Acetophenone Derivative	Proprietary Data		2.323	mg
			Supplier	Carbon Black (C)	1333-86-4		0.3872	mg

			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.3872	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	4.6436	mg
			Supplier	Copper (Cu)	7440-50-8	56.1453	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	11.9916	mg
Wire Bond - Au	0.45	mg	Supplier	Gold (Au)	7440-57-5	0.45	mg